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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	2.7 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	-
Number of I/O	96
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4128v-27tn144c

IEEE 1532-Compliant In-System Programming

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispMACH 4000 devices provide In-System Programming (ISP™) capability through the Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, users get the benefit of a standard, well-defined interface. All ispMACH 4000 devices are also compliant with the IEEE 1532 standard.

The ispMACH 4000 devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispMACH 4000 devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4000 devices during the testing of a circuit board.

User Electronic Signature

The User Electronic Signature (UES) allows the designer to include identification bits or serial numbers inside the device, stored in E²CMOS memory. The ispMACH 4000 device contains 32 UES bits that can be configured by the user to store unique data such as ID codes, revision numbers or inventory control codes.

Security Bit

A programmable security bit is provided on the ispMACH 4000 devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

Hot Socketing

The ispMACH 4000 devices are well-suited for applications that require hot socketing capability. Hot socketing a device requires that the device, during power-up and down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of I/O pin loading be minimal on active signals. The ispMACH 4000 devices provide this capability for input voltages in the range 0V to 3.0V.

Density Migration

The ispMACH 4000 family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Absolute Maximum Ratings^{1, 2, 3}

	ispMACH 4000C/Z (1.8V)	ispMACH 4000B (2.5V)	ispMACH 4000V (3.3V)
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V	-0.5 to 4.5V
Input or I/O Tristate Voltage Applied ^{4, 5}	-0.5 to 5.5V	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C	-65 to 150°C
Junction Temperature (T_j) with Power Applied	-55 to 150°C	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Undershoot of -2V and overshoot of (V_{IH} (MAX) + 2V), up to a total pin voltage of 6.0V, is permitted for a duration of < 20ns.
5. Maximum of 64 I/Os per device with $V_{IN} > 3.6V$ is allowed.

Recommended Operating Conditions

Symbol	Parameter		Min.	Max.	Units
V _{CC}	Supply Voltage for 1.8V Devices	ispMACH 4000C	1.65	1.95	V
		ispMACH 4000Z	1.7	1.9	V
		ispMACH 4000Z, Extended Functional Voltage Operation	1.6 ^{1, 2}	1.9	V
	Supply Voltage for 2.5V Devices		2.3	2.7	V
	Supply Voltage for 3.3V Devices		3.0	3.6	V
T _j	Junction Temperature (Commercial)		0	90	C
	Junction Temperature (Industrial)		-40	105	C
	Junction Temperature (Extended)		-40	130	C

1. Devices operating at 1.6V can expect performance degradation up to 35%.
2. Applicable for devices with 2004 date codes and later. Contact factory for ordering instructions.

Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle	1,000	—	Cycles

Note: Valid over commercial temperature range.

Hot Socketing Characteristics^{1,2,3}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	$0 \leq V_{IN} \leq 3.0V$, $T_j = 105^\circ C$	—	± 30	± 150	μA
		$0 \leq V_{IN} \leq 3.0V$, $T_j = 130^\circ C$	—	± 30	± 200	μA

1. Insensitive to sequence of V_{CC} or V_{CCO} . However, assumes monotonic rise/fall rates for V_{CC} and V_{CCO} , provided $(V_{IN} - V_{CCO}) \leq 3.6V$.
2. $0 < V_{CC} < V_{CC} (MAX)$, $0 < V_{CCO} < V_{CCO} (MAX)$.
3. I_{DK} is additive to I_{PU} , I_{PD} or I_{BH} . Device defaults to pull-up until fuse circuitry is active.

Supply Current, ispMACH 4000V/B/C (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{CC}^{4}	Standby Power Supply Current	$V_{CC} = 3.3V$	—	13	—	mA
		$V_{CC} = 2.5V$	—	13	—	mA
		$V_{CC} = 1.8V$	—	3	—	mA

1. $T_A = 25^{\circ}C$, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I_{CC} varies with specific device configuration and operating frequency.
4. $T_A = 25^{\circ}C$

Supply Current, ispMACH 4000Z

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	50	—	μA
		Vcc = 1.9V, T _A = 70°C	—	58	—	μA
		Vcc = 1.9V, T _A = 85°C	—	60	—	μA
		Vcc = 1.9V, T _A = 125°C	—	70	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	10	—	μA
		Vcc = 1.9V, T _A = 70°C	—	13	20	μA
		Vcc = 1.9V, T _A = 85°C	—	15	25	μA
		Vcc = 1.9V, T _A = 125°C	—	22	—	μA
ispMACH 4064ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	80	—	μA
		Vcc = 1.9V, T _A = 70°C	—	89	—	μA
		Vcc = 1.9V, T _A = 85°C	—	92	—	μA
		Vcc = 1.9V, T _A = 125°C	—	109	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	11	—	μA
		Vcc = 1.9V, T _A = 70°C	—	15	25	μA
		Vcc = 1.9V, T _A = 85°C	—	18	35	μA
		Vcc = 1.9V, T _A = 125°C	—	37	—	μA
ispMACH 4128ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	168	—	μA
		Vcc = 1.9V, T _A = 70°C	—	190	—	μA
		Vcc = 1.9V, T _A = 85°C	—	195	—	μA
		Vcc = 1.9V, T _A = 125°C	—	212	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	12	—	μA
		Vcc = 1.9V, T _A = 70°C	—	16	35	μA
		Vcc = 1.9V, T _A = 85°C	—	19	50	μA
		Vcc = 1.9V, T _A = 125°C	—	42	—	μA

Supply Current, ispMACH 4000Z (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4256ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	341	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	361	—	μA
		V _{CC} = 1.9V, T _A = 85°C	—	372	—	μA
		V _{CC} = 1.9V, T _A = 125°C	—	468	—	μA
ICC ^{4, 5}	Standby Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	13	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	32	55	μA
		V _{CC} = 1.9V, T _A = 85°C	—	43	90	μA
		V _{CC} = 1.9V, T _A = 125°C	—	135	—	μA

1. T_A = 25°C, frequency = 1.0 MHz.

2. Device configured with 16-bit counters.

3. I_{CC} varies with specific device configuration and operating frequency.

4. V_{CCO} = 3.6V, V_{IN} = 0V or V_{CCO}, bus maintenance turned off. V_{IN} above V_{CCO} will add transient current above the specified standby I_{CC}.

5. Includes V_{CCO} current without output loading.

ispMACH 4000V/B/C External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-25		-27		-3		-35		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	2.5	—	2.7	—	3.0	—	3.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	3.2	—	3.5	—	3.8	—	4.2	ns
t _S	GLB register setup time before clock	1.8	—	1.8	—	2.0	—	2.0	—	ns
t _{ST}	GLB register setup time before clock with T-type register	2.0	—	2.0	—	2.2	—	2.2	—	ns
t _{SIR}	GLB register setup time before clock, input register path	0.7	—	1.0	—	1.0	—	1.0	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	1.7	—	2.0	—	2.0	—	2.0	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	0.9	—	1.0	—	1.0	—	1.0	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	2.2	—	2.7	—	2.7	—	2.7	ns
t _R	External reset pin to output delay	—	3.5	—	4.0	—	4.4	—	4.5	ns
t _{RW}	External reset pulse duration	1.5	—	1.5	—	1.5	—	1.5	-	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	4.0	—	4.5	—	5.0	—	5.5	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	5.0	—	6.5	—	8.0	—	8.0	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	3.0	—	3.5	—	4.0	—	4.5	ns
t _{CW}	Global clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{WIR}	Input register clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	400	—	333	—	322	—	322	MHz
f _{MAX} (Ext.)	Clock frequency with external feedback, [1/ (t _S + t _{CO})]	—	250	—	222	—	212	—	212	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GPTOE}	Global PT OE Delay	—	5.58	—	5.58	—	5.78	ns
t _{PTOE}	Macrocell PT OE Delay	—	3.58	—	4.28	—	4.28	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000Z Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GPTOE}	Global PT OE Delay	—	1.9	—	2.35	—	2.60	ns
t _{PPTOE}	Macrocell PT OE Delay	—	2.4	—	3.35	—	2.60	ns

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the timing model in this data sheet for further details.

Timing v.2.2

ispMACH 4000Z Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{P_{TOE}}	Macrocell PT OE Delay	—	2.50	—	2.70	—	2.00	ns

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the timing model in this data sheet for further details.

Timing v.2.2

ispMACH 4000Z Timing Adders¹

Adder Type	Base Parameter	Description	-35		-37		-42		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t _{INDIO}	t _{INREG}	Input register delay	—	1.00	—	1.00	—	1.30	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.40	—	0.40	—	0.45	ns
t _{ORP}	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t _{BLA}	t _{ROUTE}	Additional block load-ing adder	—	0.04	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters									
LVTTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters									
LVTTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

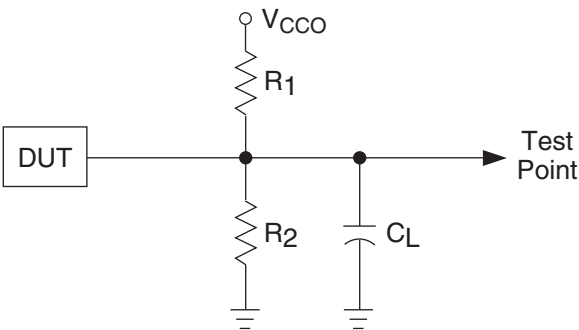
Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding the use of these adders.

Switching Test Conditions

Figure 12 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 11.

Figure 12. Output Test Load, LVTTTL and LVCMOS Standards



0213A/ispm4k

Table 11. Test Fixture Required Components

Test Condition	R_1	R_2	C_L^1	Timing Ref.	V_{CCO}
LVCMOS I/O, (L -> H, H -> L)	106 Ω	106 Ω	35pF	LVCMOS 3.3 = 1.5V	LVCMOS 3.3 = 3.0V
				LVCMOS 2.5 = $V_{CCO}/2$	LVCMOS 2.5 = 2.3V
				LVCMOS 1.8 = $V_{CCO}/2$	LVCMOS 1.8 = 1.65V
LVCMOS I/O (Z -> H)	∞	106 Ω	35pF	1.5V	3.0V
LVCMOS I/O (Z -> L)	106 Ω	∞	35pF	1.5V	3.0V
LVCMOS I/O (H -> Z)	∞	106 Ω	5pF	$V_{OH} - 0.3$	3.0V
LVCMOS I/O (L -> Z)	106 Ω	∞	5pF	$V_{OL} + 0.3$	3.0V

1. C_L includes test fixtures and probe capacitance.

Signal Descriptions

Signal Names	Description
TMS	Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK	Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO	These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND	Ground
NC	Not Connected
V _{CC}	The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I	These pins are configured to be either CLK input or as an input.
V _{CC00} , V _{CC01}	The power supply pins for each I/O bank.
yzz	Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
	ispMACH 4032 y: A-B
	ispMACH 4064 y: A-D
	ispMACH 4128 y: A-H
	ispMACH 4256 y: A-P
	ispMACH 4384 y: A-P, AX-HX
	ispMACH 4512 y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB		4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	10 I/Os / GLB	8 I/Os / GLB		8 I/Os / GLB	8 I/Os / GLB 4 I/Os / GLB

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z	4064Z		4128Z		4256Z		
Number of I/Os	32	32	64	64	96	64	96 ¹	128
Number of GLBs	2	4	4	8	8	16	16	16
Number of I/Os / GLB	16	8	16	8	12	4	8	8
Reference ORP Table	16 I/Os / GLB	8 I/Os / GLB	16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
42	1	C1	C ¹	E2	E ¹	I6	I ¹
43	1	C2	C ²	E4	E ²	I10	I ²
44	1	C3	C ³	E6	E ³	I12	I ³
45	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
46	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
47	1	C4	C ⁴	E8	E ⁴	J2	J ⁰
48	1	C5	C ⁵	E10	E ⁵	J6	J ¹
49	1	C6	C ⁶	E12	E ⁶	J10	J ²
50	1	C7	C ⁷	E14	E ⁷	J12	J ³
51	-	GND	-	GND	-	GND	-
52	-	TMS	-	TMS	-	TMS	-
53	1	C8	C ⁸	F0	F ⁰	K12	K ³
54	1	C9	C ⁹	F2	F ¹	K10	K ²
55	1	C10	C ¹⁰	F4	F ²	K6	K ¹
56	1	C11	C ¹¹	F6	F ³	K2	K ⁰
57	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
58	1	C12	C ¹²	F8	F ⁴	L12	L ³
59	1	C13	C ¹³	F10	F ⁵	L10	L ²
60	1	C14	C ¹⁴	F12	F ⁶	L6	L ¹
61	1	C15	C ¹⁵	F13	F ⁷	L4	L ⁰
62*	1	I	-	I	-	I	-
63	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
64	1	D15	D ¹⁵	G14	G ⁷	M4	M ⁰
65	1	D14	D ¹⁴	G12	G ⁶	M6	M ¹
66	1	D13	D ¹³	G10	G ⁵	M10	M ²
67	1	D12	D ¹²	G8	G ⁴	M12	M ³
68	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
69	1	D11	D ¹¹	G6	G ³	N2	N ⁰
70	1	D10	D ¹⁰	G5	G ²	N6	N ¹
71	1	D9	D ⁹	G4	G ¹	N10	N ²
72	1	D8	D ⁸	G2	G ⁰	N12	N ³
73*	1	I	-	I	-	I	-
74	-	TDO	-	TDO	-	TDO	-
75	-	VCC	-	VCC	-	VCC	-
76	-	GND	-	GND	-	GND	-
77*	1	I	-	I	-	I	-
78	1	D7	D ⁷	H13	H ⁷	O12	O ³
79	1	D6	D ⁶	H12	H ⁶	O10	O ²
80	1	D5	D ⁵	H10	H ⁵	O6	O ¹
81	1	D4	D ⁴	H8	H ⁴	O2	O ⁰
82	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
19	0	C13	C ¹⁰
20	0	C12	C ⁹
21	0	C10	C ⁸
22	0	C9	C ⁷
23	0	C8	C ⁶
24	0	GND (Bank 0)	-
25	0	C6	C ⁵
26	0	C5	C ⁴
27	0	C4	C ³
28	0	C2	C ²
29	0	C0	C ⁰
30	0	VCCO (Bank 0)	-
31	0	TCK	-
32	0	VCC	-
33	0	GND	-
34	0	D14	D ¹¹
35	0	D13	D ¹⁰
36	0	D12	D ⁹
37	0	D10	D ⁸
38	0	D9	D ⁷
39	0	D8	D ⁶
40	0	GND (Bank 0)	-
41	0	VCCO (Bank 0)	-
42	0	D6	D ⁵
43	0	D5	D ⁴
44	0	D4	D ³
45	0	D2	D ²
46	0	D1	D ¹
47	0	D0	D ⁰
48	0	CLK1/I	-
49	1	GND (Bank 1)	-
50	1	CLK2/I	-
51	1	VCC	-
52	1	E0	E ⁰
53	1	E1	E ¹
54	1	E2	E ²
55	1	E4	E ³
56	1	E5	E ⁴
57	1	E6	E ⁵
58	1	VCCO (Bank 1)	-
59	1	GND (Bank 1)	-
60	1	E8	E ⁶
61	1	E9	E ⁷

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C ⁷	C14	C ⁹	C14	C ⁷	C14	C ⁷
F5	0	C12	C ⁶	C12	C ⁸	C12	C ⁶	C12	C ⁶
D3	0	C10	C ⁵	C10	C ⁷	C10	C ⁵	C10	C ⁵
C1	0	C8	C ⁴	C9	C ⁶	C8	C ⁴	C8	C ⁴
C2	0	C6	C ³	C8	C ⁵	C6	C ³	C6	C ³
E3	0	C4	C ²	C6	C ⁴	C4	C ²	C4	C ²
D2	0	C2	C ¹	C4	C ³	C2	C ¹	C2	C ¹
F6	0	C0	C ⁰	C2	C ²	C0	C ⁰	C0	C ⁰
D1	0	NC	-	C1	C ¹	F6	F ³	H0	H ⁰
E2	0	NC	-	C0	C ⁰	F4	F ²	H4	H ¹
E4	0	NC	-	NC	-	D6	D ³	F4	F ²
G5	0	NC	-	NC	-	D4	D ²	F6	F ³
E1	0	NC	-	NC	-	NC	-	F8	F ⁴
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F ⁵
F1	0	NC	-	NC	-	D2	D ¹	F12	F ⁶
G1	0	NC	-	NC	-	D0	D ⁰	F14	F ⁷
G6	0	NC	-	D14	D ⁹	F2	F ¹	H8	H ²
G4	0	NC	-	D12	D ⁸	F0	F ⁰	H12	H ³
H6	0	D14	D ⁷	D10	D ⁷	E14	E ⁷	G14	G ⁷
G3	0	D12	D ⁶	D9	D ⁶	E12	E ⁶	G12	G ⁶
H5	0	D10	D ⁵	D8	D ⁵	E10	E ⁵	G10	G ⁵
G2	0	D8	D ⁴	D6	D ⁴	E8	E ⁴	G8	G ⁴
H1	0	D6	D ³	D4	D ³	E6	E ³	G6	G ³
H2	0	D4	D ²	D2	D ²	E4	E ²	G4	G ²
H3	0	D2	D ¹	D1	D ¹	E2	E ¹	G2	G ¹
H4	0	D0	D ⁰	D0	D ⁰	E0	E ⁰	G0	G ⁰
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E ⁰	E0	E ⁰	H0	H ⁰	J0	J ⁰
J3	0	E2	E ¹	E1	E ¹	H2	H ¹	J2	J ¹
J2	0	E4	E ²	E2	E ²	H4	H ²	J4	J ²
J1	0	E6	E ³	E4	E ³	H6	H ³	J6	J ³
K1	0	E8	E ⁴	E6	E ⁴	H8	H ⁴	J8	J ⁴
J5	0	E10	E ⁵	E8	E ⁵	H10	H ⁵	J10	J ⁵
K2	0	E12	E ⁶	E9	E ⁶	H12	H ⁶	J12	J ⁶

ispMACH 4000C (1.8V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128C	LC4128C-27T128C	128	1.8	2.7	TQFP	128	92	C
	LC4128C-5T128C	128	1.8	5	TQFP	128	92	C
	LC4128C-75T128C	128	1.8	7.5	TQFP	128	92	C
	LC4128C-27T100C	128	1.8	2.7	TQFP	100	64	C
	LC4128C-5T100C	128	1.8	5	TQFP	100	64	C
	LC4128C-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256C	LC4256C-3FT256AC	256	1.8	3	ftBGA	256	128	C
	LC4256C-5FT256AC	256	1.8	5	ftBGA	256	128	C
	LC4256C-75FT256AC	256	1.8	7.5	ftBGA	256	128	C
	LC4256C-3FT256BC	256	1.8	3	ftBGA	256	160	C
	LC4256C-5FT256BC	256	1.8	5	ftBGA	256	160	C
	LC4256C-75FT256BC	256	1.8	7.5	ftBGA	256	160	C
	LC4256C-3F256AC ¹	256	1.8	3	fpBGA	256	128	C
	LC4256C-5F256AC ¹	256	1.8	5	fpBGA	256	128	C
	LC4256C-75F256AC ¹	256	1.8	7.5	fpBGA	256	128	C
	LC4256C-3F256BC ¹	256	1.8	3	fpBGA	256	160	C
	LC4256C-5F256BC ¹	256	1.8	5	fpBGA	256	160	C
	LC4256C-75F256BC ¹	256	1.8	7.5	fpBGA	256	160	C
	LC4256C-3T176C	256	1.8	3	TQFP	176	128	C
	LC4256C-5T176C	256	1.8	5	TQFP	176	128	C
	LC4256C-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256C-3T100C	256	1.8	3	TQFP	100	64	C
	LC4256C-5T100C	256	1.8	5	TQFP	100	64	C
	LC4256C-75T100C	256	1.8	7.5	TQFP	100	64	C
LC4384C	LC4384C-35FT256C	384	1.8	3.5	ftBGA	256	192	C
	LC4384C-5FT256C	384	1.8	5	ftBGA	256	192	C
	LC4384C-75FT256C	384	1.8	7.5	ftBGA	256	192	C
	LC4384C-35F256C ¹	384	1.8	3.5	fpBGA	256	192	C
	LC4384C-5F256C ¹	384	1.8	5	fpBGA	256	192	C
	LC4384C-75F256C ¹	384	1.8	7.5	fpBGA	256	192	C
	LC4384C-35T176C	384	1.8	3.5	TQFP	176	128	C
	LC4384C-5T176C	384	1.8	5	TQFP	176	128	C
	LC4384C-75T176C	384	1.8	7.5	TQFP	176	128	C
LC4512C	LC4512C-35FT256C	512	1.8	3.5	ftBGA	256	208	C
	LC4512C-5FT256C	512	1.8	5	ftBGA	256	208	C
	LC4512C-75FT256C	512	1.8	7.5	ftBGA	256	208	C
	LC4512C-35F256C ¹	512	1.8	3.5	fpBGA	256	208	C
	LC4512C-5F256C ¹	512	1.8	5	fpBGA	256	208	C
	LC4512C-75F256C ¹	512	1.8	7.5	fpBGA	256	208	C
	LC4512C-35T176C	512	1.8	3.5	TQFP	176	128	C
	LC4512C-5T176C	512	1.8	5	TQFP	176	128	C
	LC4512C-75T176C	512	1.8	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000C (1.8V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032C-75T48I	32	1.8	7.5	TQFP	48	32	I
	LC4032C-10T48I	32	1.8	10	TQFP	48	32	I
	LC4032C-5T44I	32	1.8	5	TQFP	44	30	I
	LC4032C-75T44I	32	1.8	7.5	TQFP	44	30	I
	LC4032C-10T44I	32	1.8	10	TQFP	44	30	I
LC4064C	LC4064C-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064C-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064C-10T100I	64	1.8	10	TQFP	100	64	I
	LC4064C-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064C-75T48I	64	1.8	7.5	TQFP	48	32	I
	LC4064C-10T48I	64	1.8	10	TQFP	48	32	I
	LC4064C-5T44I	64	1.8	5	TQFP	44	30	I
	LC4064C-75T44I	64	1.8	7.5	TQFP	44	30	I
	LC4064C-10T44I	64	1.8	10	TQFP	44	30	I
LC4128C	LC4128C-5T128I	128	1.8	5	TQFP	128	92	I
	LC4128C-75T128I	128	1.8	7.5	TQFP	128	92	I
	LC4128C-10T128I	128	1.8	10	TQFP	128	92	I
	LC4128C-5T100I	128	1.8	5	TQFP	100	64	I
	LC4128C-75T100I	128	1.8	7.5	TQFP	100	64	I
	LC4128C-10T100I	128	1.8	10	TQFP	100	64	I
LC4256C	LC4256C-5FT256AI	256	1.8	5	ftBGA	256	128	I
	LC4256C-75FT256AI	256	1.8	7.5	ftBGA	256	128	I
	LC4256C-10FT256AI	256	1.8	10	ftBGA	256	128	I
	LC4256C-5FT256BI	256	1.8	5	ftBGA	256	160	I
	LC4256C-75FT256BI	256	1.8	7.5	ftBGA	256	160	I
	LC4256C-10FT256BI	256	1.8	10	ftBGA	256	160	I
	LC4256C-5F256AI ¹	256	1.8	5	fpBGA	256	128	I
	LC4256C-75F256AI ¹	256	1.8	7.5	fpBGA	256	128	I
	LC4256C-10F256AI ¹	256	1.8	10	fpBGA	256	128	I
	LC4256C-5F256BI ¹	256	1.8	5	fpBGA	256	160	I
	LC4256C-75F256BI ¹	256	1.8	7.5	fpBGA	256	160	I
	LC4256C-10F256BI ¹	256	1.8	10	fpBGA	256	160	I
	LC4256C-5T176I	256	1.8	5	TQFP	176	128	I
	LC4256C-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256C-10T176I	256	1.8	10	TQFP	176	128	I
	LC4256C-5T100I	256	1.8	5	TQFP	100	64	I
	LC4256C-75T100I	256	1.8	7.5	TQFP	100	64	I
	LC4256C-10T100I	256	1.8	10	TQFP	100	64	I

Lead-Free Packaging**ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Commercial Devices**

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35MN56C	32	1.8	3.5	Lead-free csBGA	56	32	C
	LC4032ZC-5MN56C	32	1.8	5	Lead-free csBGA	56	32	C
	LC4032ZC-75MN56C	32	1.8	7.5	Lead-free csBGA	56	32	C
	LC4032ZC-35TN48C	32	1.8	3.5	Lead-free TQFP	48	32	C
	LC4032ZC-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032ZC-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
LC4064ZC	LC4064ZC-37MN132C	64	1.8	3.7	Lead-free csBGA	132	64	C
	LC4064ZC-5MN132C	64	1.8	5	Lead-free csBGA	132	64	C
	LC4064ZC-75MN132C	64	1.8	7.5	Lead-free csBGA	132	64	C
	LC4064ZC-37TN100C	64	1.8	3.7	Lead-free TQFP	100	64	C
	LC4064ZC-5TN100C	64	1.8	5	Lead-free TQFP	100	64	C
	LC4064ZC-75TN100C	64	1.8	7.5	Lead-free TQFP	100	64	C
	LC4064ZC-37MN56C	64	1.8	3.7	Lead-free csBGA	56	32	C
	LC4064ZC-5MN56C	64	1.8	5	Lead-free csBGA	56	32	C
	LC4064ZC-75MN56C	64	1.8	7.5	Lead-free csBGA	56	32	C
	LC4064ZC-37TN48C	64	1.8	3.7	Lead-free TQFP	48	32	C
	LC4064ZC-5TN48C	64	1.8	5	Lead-free TQFP	48	32	C
	LC4064ZC-75TN48C	64	1.8	7.5	Lead-free TQFP	48	32	C
LC4128ZC	LC4128ZC-42MN132C	128	1.8	4.2	Lead-free csBGA	132	96	C
	LC4128ZC-75MN132C	128	1.8	7.5	Lead-free csBGA	132	96	C
	LC4128ZC-42TN100C	128	1.8	4.2	Lead-free TQFP	100	64	C
	LC4128ZC-75TN100C	128	1.8	7.5	Lead-free TQFP	100	64	C
LC4256ZC	LC4256ZC-45TN176C	256	1.8	4.5	Lead-free TQFP	176	128	C
	LC4256ZC-75TN176C	256	1.8	7.5	Lead-free TQFP	176	128	C
	LC4256ZC-45MN132C	256	1.8	4.5	Lead-free csBGA	132	96	C
	LC4256ZC-75MN132C	256	1.8	7.5	Lead-free csBGA	132	96	C
	LC4256ZC-45TN100C	256	1.8	4.5	Lead-free TQFP	100	64	C
	LC4256ZC-75TN100C	256	1.8	7.5	Lead-free TQFP	100	64	C

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5MN56I	32	1.8	5	Lead-free csBGA	56	32	I
	LC4032ZC-75MN56I	32	1.8	7.5	Lead-free csBGA	56	32	I
	LC4032ZC-5TN48I	32	1.8	5	Lead-free TQFP	48	32	I
	LC4032ZC-75TN48I	32	1.8	7.5	Lead-free TQFP	48	32	I

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4064ZC	LC4064ZC-5MN132I	64	1.8	5	Lead-free csBGA	132	64	I
	LC4064ZC-75MN132I	64	1.8	7.5	Lead-free csBGA	132	64	I
	LC4064ZC-5TN100I	64	1.8	5	Lead-free TQFP	100	64	I
	LC4064ZC-75TN100I	64	1.8	7.5	Lead-free TQFP	100	64	I
	LC4064ZC-5MN56I	64	1.8	5	Lead-free csBGA	56	32	I
	LC4064ZC-75MN56I	64	1.8	7.5	Lead-free csBGA	56	32	I
	LC4064ZC-5TN48I	64	1.8	5	Lead-free TQFP	48	32	I
	LC4064ZC-75TN48I	64	1.8	7.5	Lead-free TQFP	48	32	I
LC4128ZC	LC4128ZC-75MN132I	128	1.8	7.5	Lead-free csBGA	132	96	I
	LC4128ZC-75TN100I	128	1.8	7.5	Lead-free TQFP	100	64	I
LC4256ZC	LC4256ZC-75TN176I	256	1.8	7.5	Lead-free TQFP	176	128	I
	LC4256ZC-75MN132I	256	1.8	7.5	Lead-free csBGA	132	96	I
	LC4256ZC-75TN100I	256	1.8	7.5	Lead-free TQFP	100	64	I

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-75TN48E	32	1.8	7.5	Lead-free TQFP	48	32	E
LC4064ZC	LC4064ZC-75TN100E	64	1.8	7.5	Lead-free TQFP	100	64	E
	LC4064ZC-75TN48E	64	1.8	7.5	Lead-free TQFP	48	32	E
LC4128ZC	LC4128ZC-75TN100E	128	1.8	7.5	Lead-free TQFP	100	64	E
LC4256ZC	LC4256ZC-75TN176E	256	1.8	7.5	Lead-free TQFP	176	128	E
	LC4256ZC-75TN100E	256	1.8	7.5	Lead-free TQFP	100	64	E

ispMACH 4000C (1.8V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-25TN48C	32	1.8	2.5	Lead-free TQFP	48	32	C
	LC4032C-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032C-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
	LC4032C-25TN44C	32	1.8	2.5	Lead-free TQFP	44	30	C
	LC4032C-5TN44C	32	1.8	5	Lead-free TQFP	44	30	C
	LC4032C-75TN44C	32	1.8	7.5	Lead-free TQFP	44	30	C

ispMACH 4000B (2.5V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384B	LC4384B-35FTN256C	384	2.5	3.5	Lead-Free ftBGA	256	192	C
	LC4384B-5FTN256C	384	2.5	5	Lead-Free ftBGA	256	192	C
	LC4384B-75FTN256C	384	2.5	7.5	Lead-Free ftBGA	256	192	C
	LC4384B-35FN256C ¹	384	2.5	3.5	Lead-Free fpBGA	256	192	C
	LC4384B-5FN256C ¹	384	2.5	5	Lead-Free fpBGA	256	192	C
	LC4384B-75FN256C ¹	384	2.5	7.5	Lead-Free fpBGA	256	192	C
	LC4384B-35TN176C	384	2.5	3.5	Lead-Free TQFP	176	128	C
	LC4384B-5TN176C	384	2.5	5	Lead-Free TQFP	176	128	C
	LC4384B-75TN176C	384	2.5	7.5	Lead-Free TQFP	176	128	C
LC4512B	LC4512B-35FTN256C	512	2.5	3.5	Lead-Free ftBGA	256	208	C
	LC4512B-5FTN256C	512	2.5	5	Lead-Free ftBGA	256	208	C
	LC4512B-75FTN256C	512	2.5	7.5	Lead-Free ftBGA	256	208	C
	LC4512B-35FN256C ¹	512	2.5	3.5	Lead-Free fpBGA	256	208	C
	LC4512B-5FN256C ¹	512	2.5	5	Lead-Free fpBGA	256	208	C
	LC4512B-75FN256C ¹	512	2.5	7.5	Lead-Free fpBGA	256	208	C
	LC4512B-35TN176C	512	2.5	3.5	Lead-Free TQFP	176	128	C
	LC4512B-5TN176C	512	2.5	5	Lead-Free TQFP	176	128	C
	LC4512B-75TN176C	512	2.5	7.5	Lead-Free TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-5TN48I	32	2.5	5	Lead-Free TQFP	48	32	I
	LC4032B-75TN48I	32	2.5	7.5	Lead-Free TQFP	48	32	I
	LC4032B-10TN48I	32	2.5	10	Lead-Free TQFP	48	32	I
	LC4032B-5TN44I	32	2.5	5	Lead-Free TQFP	44	30	I
	LC4032B-75TN44I	32	2.5	7.5	Lead-Free TQFP	44	30	I
	LC4032B-10TN44I	32	2.5	10	Lead-Free TQFP	44	30	I
LC4064B	LC4064B-5TN100I	64	2.5	5	Lead-Free TQFP	100	64	I
	LC4064B-75TN100I	64	2.5	7.5	Lead-Free TQFP	100	64	I
	LC4064B-10TN100I	64	2.5	10	Lead-Free TQFP	100	64	I
	LC4064B-5TN48I	64	2.5	5	Lead-Free TQFP	48	32	I
	LC4064B-75TN48I	64	2.5	7.5	Lead-Free TQFP	48	32	I
	LC4064B-10TN48I	64	2.5	10	Lead-Free TQFP	48	32	I
	LC4064B-5TN44I	64	2.5	5	Lead-Free TQFP	44	30	I
	LC4064B-75TN44I	64	2.5	7.5	Lead-Free TQFP	44	30	I
	LC4064B-10TN44I	64	2.5	10	Lead-Free TQFP	44	30	I

Revision History (Cont.)

Date	Version	Change Summary
January 2004	20z	ispMACH 4000Z data sheet status changed from preliminary to final. Documents production release of the ispMACH 4256Z device.
		Added new feature - ispMACH 4000Z supports operation down to 1.6V.
		Added lead-free packaging ordering part numbers for the ispMACH 4000Z/C/V devices.
April 2004	21z	Updated I_{PU} (I/O Weak Pull-up Resistor Current) max. specification for the ispMACH 4000V/B/C; -150 μ A to -200 μ A.
November 2004	22z	Added User Electronic Signature section.
		Added ispMACH 4000B (2.5V) Lead-Free Ordering Part Numbers.
December 2004	22z.1	Updated Further Information section.
February 2006	22z.2	Clarification to ispMACH 4000Z Input Leakage (I_{IH}) specification.
March 2007	22.3	Updated ispMACH 4000 Introduction section.
		Updated Signal Descriptions table.
June 2007	22.4	Updated Features bullets to include reference to “LA” automotive data sheet under the “Broad Device Offering” bullet.
		Added footnote 1 to Part Number Description to reference the “LA” automotive data sheet.
		Changed device temperature references from ‘Automotive’ to “Extended Temperature” for non-AEC-Q100 qualified devices.
November 2007	23.0	Added 256-ftBGA package Ordering Part Number information per PCN#14A-07.
May 2009	23.1	Correction to t_{CW} , t_{GW} , t_{WIR} and f_{MAX} parameters in ispMACH 4000Z External Switching Characteristics table.
		Correction to t_{CW} , t_{GW} , t_{WIR} and f_{MAX} parameters in ispMACH 4000V/B/C External Switching Characteristics table.